

Dual N-Channel Enhancement Mode Power MOSFET

Description

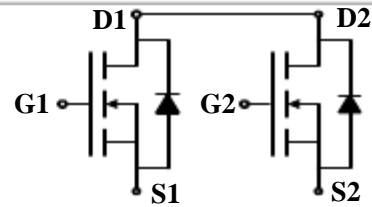
The HX8205 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

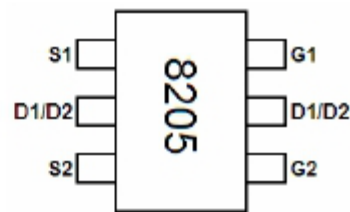
- $V_{DS} = 19.5V, I_D = 4A$
 $R_{DS(ON)} < 37m\Omega @ V_{GS}=2.5V$
 $R_{DS(ON)} < 27m\Omega @ V_{GS}=4.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

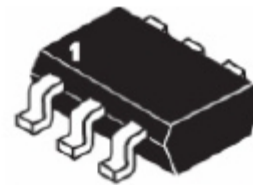
- Battery protection
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



SOT23-6L top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
8205	HX8205	SOT23-6L	Ø180mm	8mm	3000 units

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	19.5	V
Gate-Source Voltage	V_{GS}	±10	V
Drain Current-Continuous	I_D	4	A
Drain Current-Pulsed (Note 1)	I_{DM}	25	A
Maximum Power Dissipation	P_D	1.25	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C



Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	19.5	21	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =19.5V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.7	1.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =4A	-	21	27	mΩ
		V _{GS} =2.5V, I _D =3A	-	27	37	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =4A	-	10	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =8V, V _{GS} =0V, F=1.0MHz	-	800	-	PF
Output Capacitance	C _{oss}		-	155	-	PF
Reverse Transfer Capacitance	C _{rss}		-	125	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V, I _D =1A V _{GS} =4V, R _{GEN} =10Ω	-	18	-	nS
Turn-on Rise Time	t _r		-	5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	43	-	nS
Turn-Off Fall Time	t _f		-	20	-	nS
Total Gate Charge	Q _g	V _{DS} =10V, I _D =4A, V _{GS} =4.5V	-	11	-	nC
Gate-Source Charge	Q _{gs}		-	2.3	-	nC
Gate-Drain Charge	Q _{gd}		-	2.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =2A	-	0.8	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	2	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

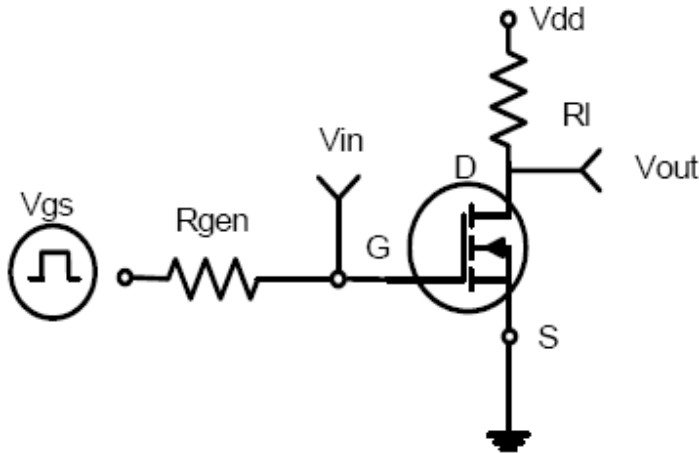


Figure 1: Switching Test Circuit

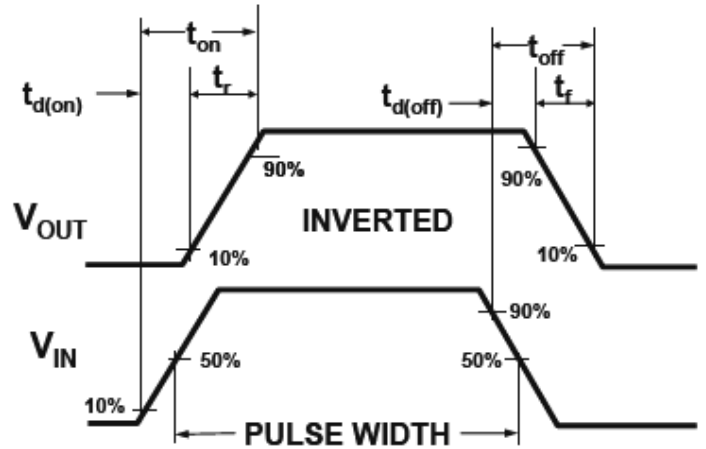


Figure 2: Switching Waveforms

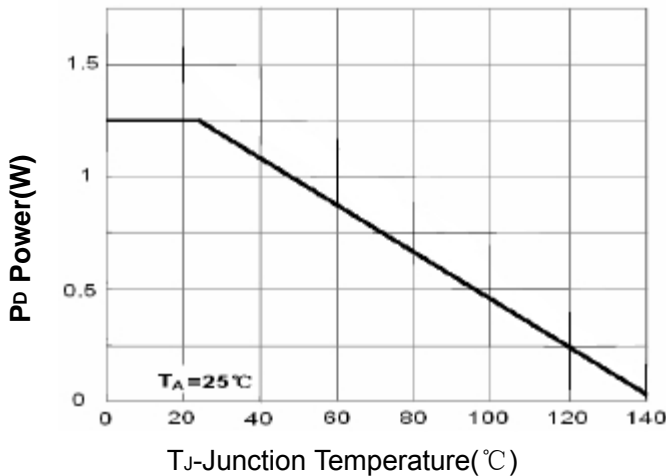


Figure 3: Power Dissipation

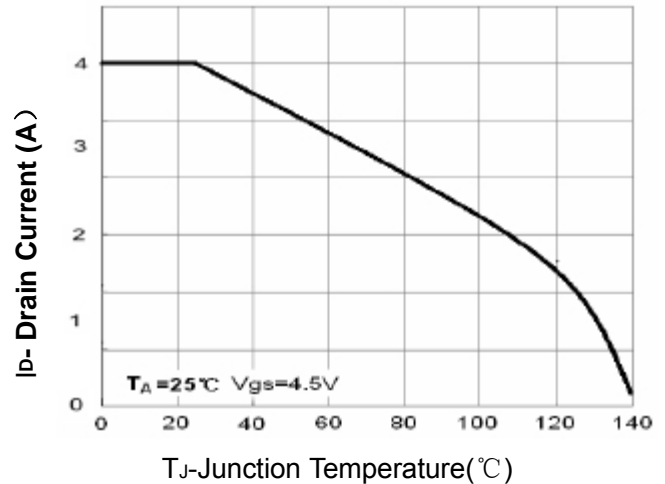


Figure 4: Drain Current

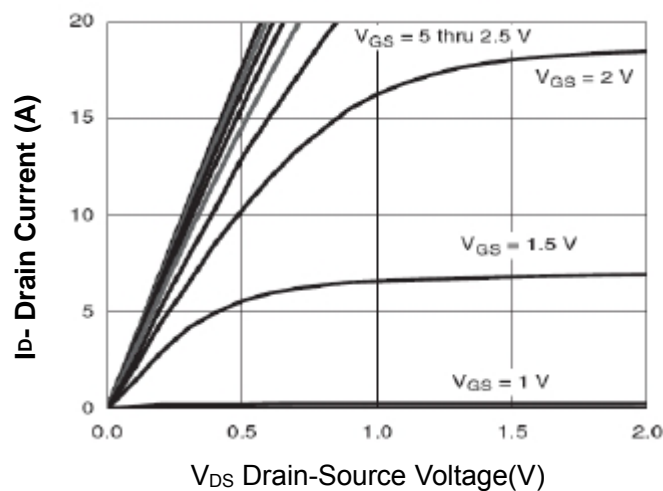


Figure 5: Output Characteristics

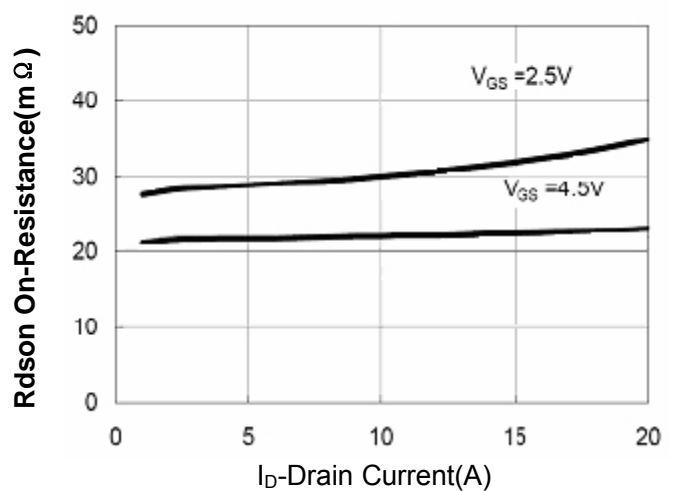


Figure 6: Drain-Source On-Resistance

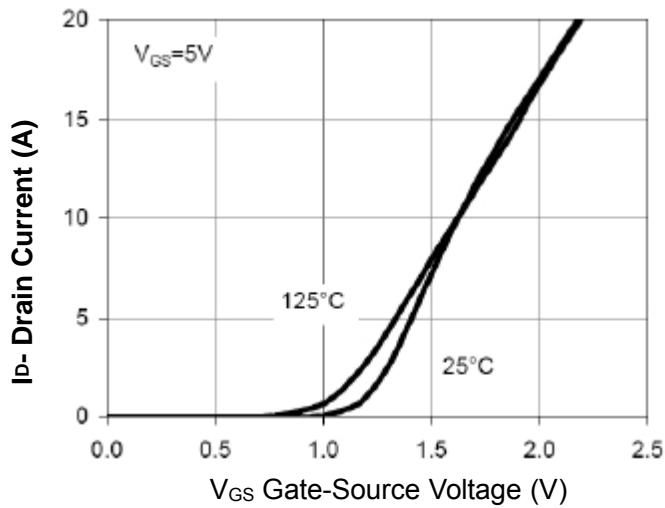


Figure 7: Transfer Characteristics

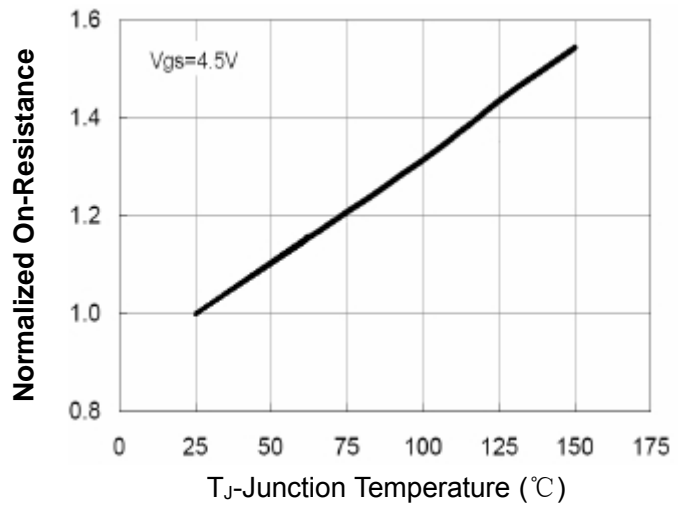


Figure 8: Drain-Source On-Resistance

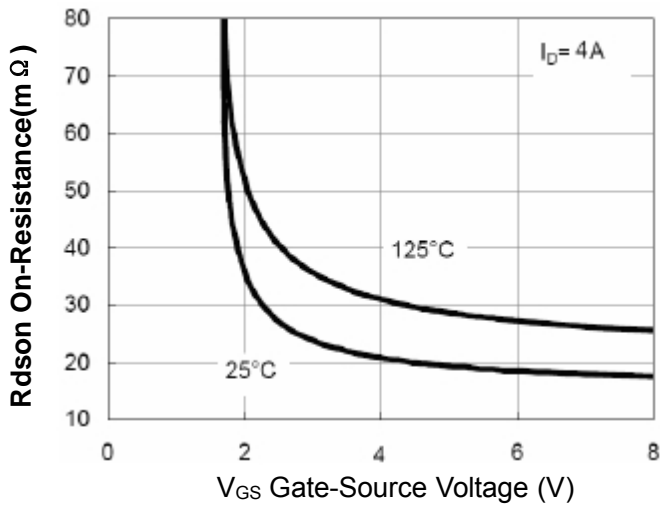


Figure 9: Rds(on) vs VGS

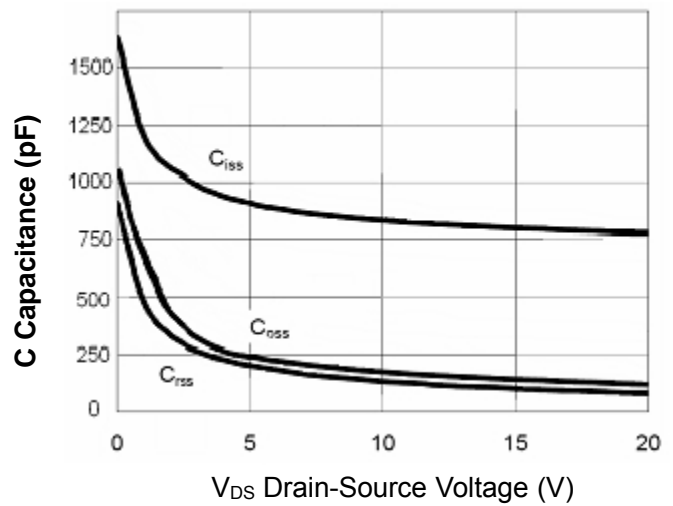


Figure 10: Capacitance vs VDS

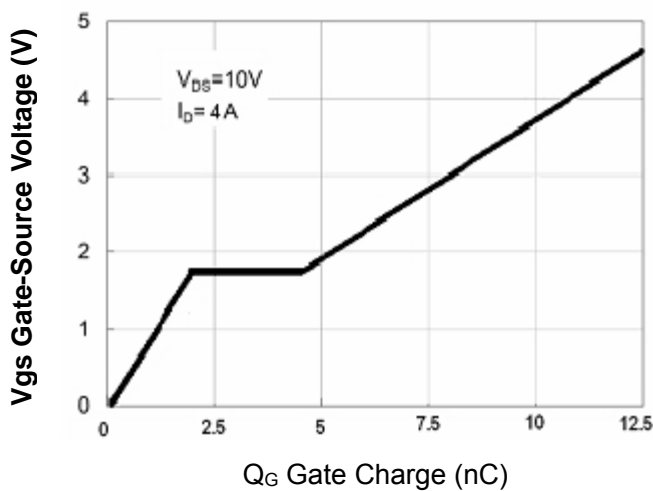


Figure 11: Gate Charge

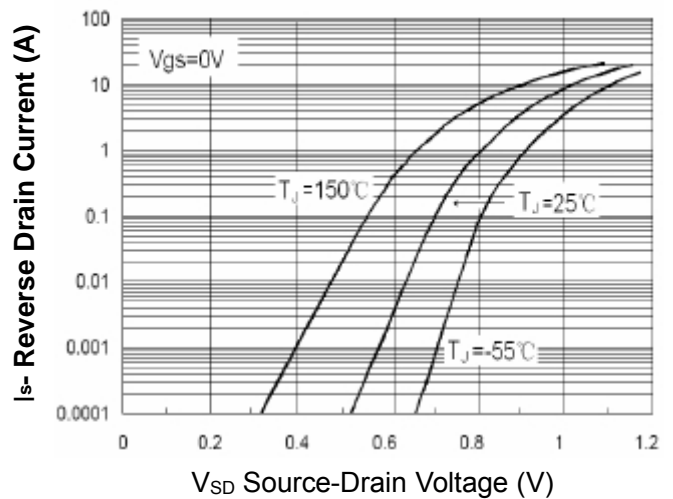


Figure 12: Source-Drain Diode Forward

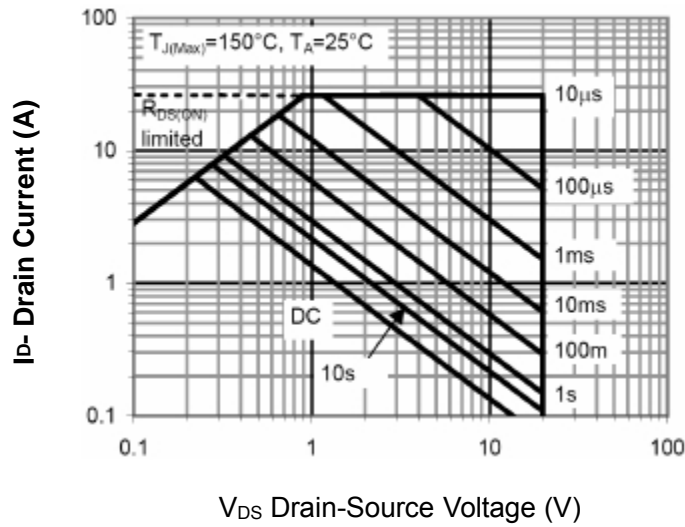


Figure 13: Safe Operation Area

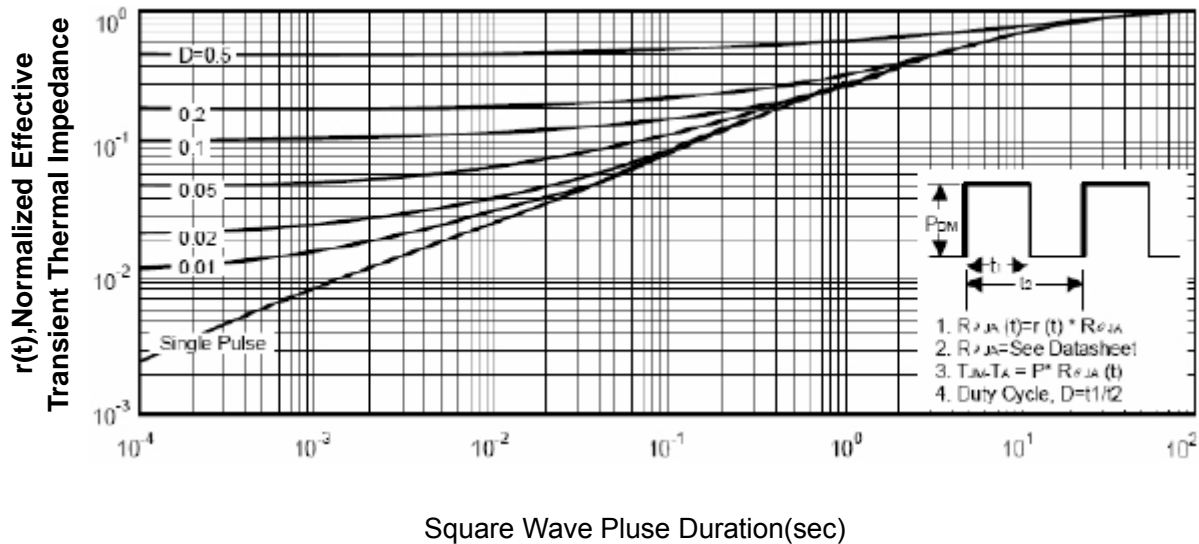
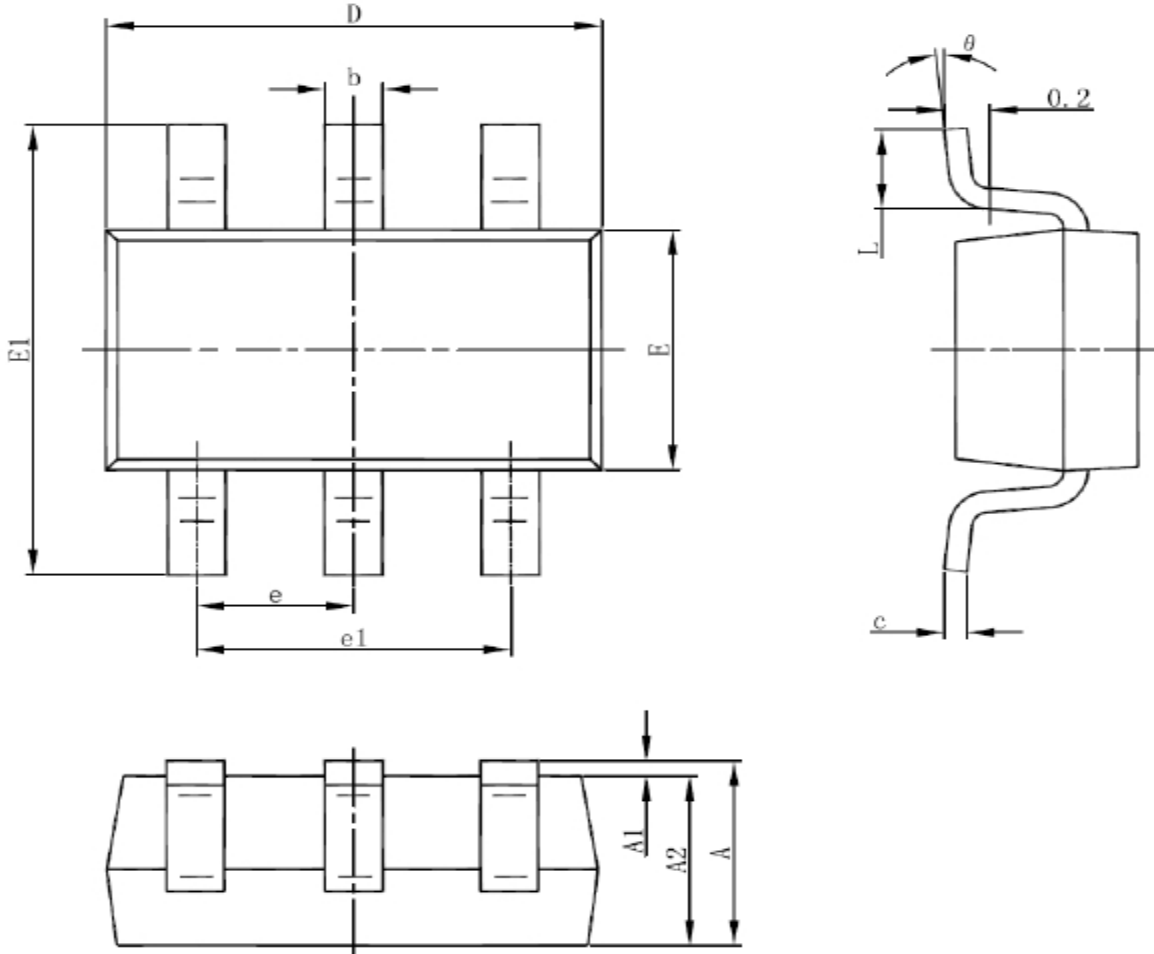


Figure 14: Normalized Maximum Transient Thermal Impedance

SOT23-6L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°